- Qualification in Accordance With AEC-Q100†
- Qualified for Automotive Applications
- Customer-Specific Configuration Control Can Be Supported Along With Major-Change Approval
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Operates From 2 V to 3.6 V
- Inputs Accept Voltages to 5.5 V
- Max t<sub>pd</sub> of 7.5 ns at 3.3 V
- Typical V<sub>OLP</sub> (Output Ground Bounce)
  <0.8 V at V<sub>CC</sub> = 3.3 V, T<sub>A</sub> = 25°C
- Typical V<sub>OHV</sub> (Output V<sub>OH</sub> Undershoot)
  >2 V at V<sub>CC</sub> = 3.3 V, T<sub>A</sub> = 25°C

 Supports Mixed-Mode Signal Operation on All Ports (5-V Input/Output Voltage With 3.3-V V<sub>CC</sub>)

 I<sub>off</sub> Supports Partial-Power-Down Mode Operation

**DW OR PW PACKAGE** 

	(TC	P VIEW	)
OE [	1	U <sub>20</sub>	
1Q [	2	19	[] 8Q
1D [	3	18	] 8D
2D [	4	17	] 7D
2Q [	5	16	] 7Q
3Q [	6	15	] 6Q
3D [	7	14	] 6D
4D [	8	13	] 5D
4Q [	9	12	] 5Q
GND [	10	11	LE

#### description/ordering information

The SN74LVC373A octal transparent D-type latch is designed for 2.7-V to 3.6-V V<sub>CC</sub> operation.

While the latch-enable (LE) input is high, the Q outputs follow the data (D) inputs. When LE is taken low, the Q outputs are latched at the logic levels set up at the D inputs.

A buffered output-enable  $(\overline{OE})$  input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or the high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without interface or pullup components.

OE does not affect the internal operations of the latches. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

This device is fully specified for partial-power-down applications using I<sub>off</sub>. The I<sub>off</sub> circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

To ensure the high-impedance state during power up or power down,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

Inputs can be driven from either 3.3-V or 5-V devices. This feature allows the use of this device as a translator in a mixed 3.3-V/5-V system environment.

#### ORDERING INFORMATION

TA	PACKAGE <sup>‡</sup>		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 125°C	SOIC - DW	Reel of 2000	SN74LVC373AQDWRQ1	L373AQ1
	TSSOP – PW	Reel of 2000	SN74LVC373AQPWRQ1	L373AQ1

<sup>&</sup>lt;sup>‡</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

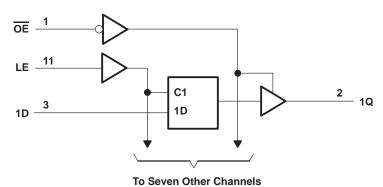


<sup>†</sup> Contact factory for details. Q100 qualification data available on request

# FUNCTION TABLE (each latch)

	INPUTS		OUTPUT
OE	LE	D	Q
L	Н	Н	Н
L	Н	L	L
L	L	Χ	$Q_0$
Н	X	Χ	Z

#### logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V <sub>CC</sub>	
Input voltage range, V <sub>I</sub> (see Note 1)	–0.5 V to 6.5 V
Voltage range applied to any output in the high-impedance or power-off state, V <sub>O</sub>	
(see Note 1)	–0.5 V to 6.5 V
Voltage range applied to any output in the high or low state, VO	
(see Notes 1 and 2)	$-0.5 \text{ V to V}_{CC} + 0.5 \text{ V}$
Input clamp current, I <sub>IK</sub> (V <sub>I</sub> < 0)	–50 mA
Output clamp current, I <sub>OK</sub> (V <sub>O</sub> < 0)	
Continuous output current, I <sub>O</sub>	±50 mA
Continuous current through V <sub>CC</sub> or GND	±100 mA
Package thermal impedance, $\theta_{JA}$ (see Note 3): DW package	58°C/W
PW package	
Storage temperature range, T <sub>stg</sub>	

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.
  - 2. The value of V<sub>CC</sub> is provided in the recommended operating conditions table.
  - 3. The package thermal impedance is calculated in accordance with JESD 51-7.



## recommended operating conditions (see Note 4)

			MIN	MAX	UNIT
.,	O make college	Operating	2	3.6	
VCC	Supply voltage	Data retention only	1.5		V
VIH	High-level input voltage	V <sub>CC</sub> = 2.7 V to 3.6 V	2		V
V <sub>IL</sub>	Low-level input voltage	$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$		0.8	V
٧ <sub>I</sub>	Input voltage		0	5.5	V
.,	Outside and to me	High or low state	0	VCC	.,
VO	Output voltage	3-state	0	5.5	V
	High level autout august	V <sub>CC</sub> = 2.7 V V <sub>CC</sub> = 3 V		-12	A
ЮН	High-level output current			-24	mA
	Law law law and a summer	V <sub>CC</sub> = 2.7 V		12	1
lOL	Low-level output current V <sub>CC</sub> = 3 V			24	mA
Δt/Δν	Input transition rise or fall rate			10	ns/V
TA	Operating free-air temperature		-40	125	°C

NOTE 4: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	vcc	MIN	TYP <sup>†</sup>	MAX	UNIT	
	I <sub>OH</sub> = -100 μA	2.7 V to 3.6 V	V <sub>CC</sub> -0.2				
l.,	404		2.7 V	2.2			v
VOH	IOH = -12  mA		3 V	2.4			V
	$I_{OH} = -24 \text{ mA}$		3 V	2.2			
	I <sub>OL</sub> = 100 μA		2.7 V to 3.6 V			0.2	
VOL	I <sub>OL</sub> = 12 mA	2.7 V			0.4	V	
	I <sub>OL</sub> = 24 mA		3 V			0.55	
II	V <sub>I</sub> = 0 to 5.5 V		3.6 V			±5	μΑ
IOZ	$V_{O} = 0 \text{ to } 5.5 \text{ V}$		3.6 V			±15	μΑ
	V <sub>I</sub> = V <sub>CC</sub> or GND		0.01/			10	
Icc	$3.6 \text{ V} \le \text{V}_{\text{I}} \le 5.5 \text{ V}^{\ddagger}$ $\text{IO} = 0$		3.6 V			10	μΑ
ΔlCC	One input at $V_{CC}$ – 0.6 V, Other inputs at $V_{CC}$ or GND		2.7 V to 3.6 V			500	μΑ
Ci	$V_I = V_{CC}$ or GND		3.3 V		4	12	pF
Co	$V_O = V_{CC}$ or GND		3.3 V		5.5	12	pF

<sup>&</sup>lt;sup>†</sup> All typical values are at  $V_{CC} = 3.3 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ .

# timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

		V <sub>CC</sub> = 2.7 V		V <sub>CC</sub> = 3.3 V ± 0.3 V		UNIT
		MIN	MAX	MIN	MAX	
t <sub>W</sub>	Pulse duration, LE high	3.3		3.3		ns
t <sub>su</sub>	Setup time, data before LE↓	2		2		ns
th	Hold time, data after LE↓	2	•	2		ns



<sup>&</sup>lt;sup>‡</sup> This applies in the disabled state only.

# **SN74LVC373A-Q1 OCTAL TRANSPARENT D-TYPE LATCH** WITH 3-STATE OUTPUTS SCAS710A - SEPTEMBER 2003 - REVISED MAY 2004

## switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

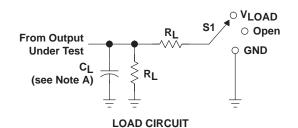
PARAMETER	FROM	TO	V <sub>CC</sub> = 2.7 V		V <sub>CC</sub> = 3.3 V ± 0.3 V		UNIT
	(INPUT)	(OUTPUT)	MIN	MAX	MIN	MAX	
	D	•		8.5	1	7.5	
<sup>t</sup> pd	LE	Q		9.5	1	8.5	ns
t <sub>en</sub>	ŌĒ	Q		8.7	1	7.7	ns
t <sub>dis</sub>	ŌĒ	Q		8	0.5	7	ns

# operating characteristics, $T_A = 25^{\circ}C$

PARAMETER		TEST CONDITIONS	V <sub>CC</sub> = 2.5 V TYP	V <sub>CC</sub> = 3.3 V	UNIT		
<u> </u>	Device discinction consistence and lately	Outputs enabled	f 40 MU-	†	46		
C <sub>pd</sub>	Power dissipation capacitance per latch	Outputs disabled	f = 10 MHz	†	3	pF	

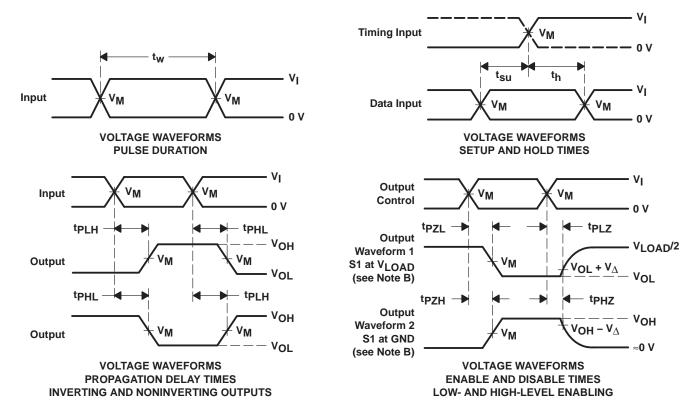
<sup>†</sup> This information was not available at the time of publication.

#### PARAMETER MEASUREMENT INFORMATION



TEST	<b>S</b> 1
tPLH/tPHL	Open
tPLZ/tPZL	V <sub>LOAD</sub>
tPHZ/tPZH	GND

	INPUTS		.,	.,		-	.,
VCC	VI	t <sub>r</sub> /t <sub>f</sub>	t <sub>r</sub> /t <sub>f</sub> V <sub>M</sub> V <sub>LOAD</sub>		CL	RL	$v_{\scriptscriptstyle\Delta}$
2.7 V	2.7 V	≤2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V
3.3 V $\pm$ 0.3 V	2.7 V	≤2.5 ns	1.5 V	6 V	50 pF	500 $\Omega$	0.3 V



NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O$  = 50  $\Omega$ .
- D. The outputs are measured one at a time, with one transition per measurement.
- E. tpLz and tpHz are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. tpLH and tpHL are the same as tpd.
- H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms



# DW (R-PDSO-G20)

## PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

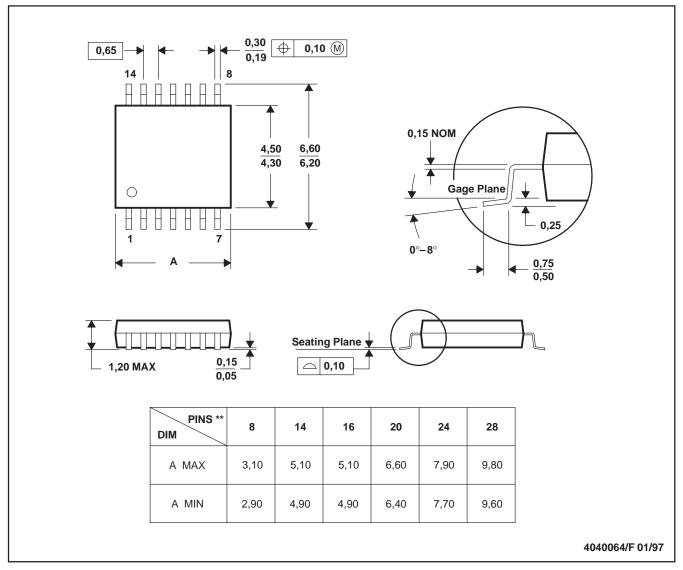
- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AC.



## PW (R-PDSO-G\*\*)

#### 14 PINS SHOWN

## PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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